

Material Composition Specification

GPR-1A Case



Device average mass 342 mg

Fluctuation margin +/-10%

Component	Material	Material		Substance	CAS No.	Substance		
		(%wt)	(mg)			(%wt)	(mg)	(ppm)
active device	doped Si	0.34%	1.16	Si	7440-21-3	0.34%	1.16	3,392
lead wire	Cu alloy	80.7%	276	Cu	7440-50-8	80.65%	275.83	806,520
				Zn	7440-66-6	0.05%	0.17	497
die attach	solder	0.5%	1.7	Cu	7440-50-8	0.4%	1.36	3,977
				Ag	7440-22-4	0.08%	0.26	760
				P	7723-14-0	0.03%	0.09	263
encapsulation	moly slug	13.39%	45.8	Mo	7439-98-7	13.39%	45.8	133,918
case	glass powder	2.92%	10	ZnO	1314-13-2	1.75%	6	17,544
				B ₂ O ₃	1303-86-2	0.88%	3	8,772
				SiO ₂	14808-60-7	0.23%	0.8	2,339
				PbO	1317-36-8	0.06%	0.2	585
plating*	tin/lead process	2.05%	7	Sn	7440-31-5	1.74%	5.96	17,427
				Pb	7439-92-1	0.3%	1.04	3,041
	100% tin process	2.05%	7	Sn	7440-31-5	2.05%	7	20,468

*For Lead Free plating, add suffix "LEAD FREE" to part number.

For Tin/Lead plating, add suffix "TIN/LEAD" to part number.

No suffix designation allows for the supply of either lead-free or tin/lead plated product depending on availability.

Disclaimer

The information provided in this Material Composition data sheet is, to the best of our knowledge, correct. However, there is no guarantee to completeness or accuracy, as some information is derived from data sources outside the company.

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